

CLAIM AMENDMENTS

IN THE CLAIMS

This listing of the claims will replace all prior versions, and listing, of claims in the application or previous response to office action:

1. (Currently Amended) [[C]]A circuit arrangement comprising:
 - a power section, which comprises heat-generating components comprising first and second chips and at least one component producing less heat,
 - the component producing less heat being arranged in an internal region of the circuit arrangement, and
 - the heat-generating components being arranged around the internal region and being mounted on one of at least onetwo metallic bodybodies acting as an electrical conductors, said bodybodies being electrically connected to the heat-generating components, wherein
 - the body isbodies are arranged in an electrically insulating manner in the region of the heat generating components on a heat sink, in order to cool the heat-generating components, and whereinsaid bodies comprising a first metallic body and a second metallic body, said first chips being mounted on the first metallic body running along the outer edge of the heat sink, and said second chips being mounted on the second metallic body covering the internal region of the heat sink.
 - the heat sink is embodied running around the internal region with the components producing less heat.
2. (Original) [[C]]A circuit arrangement according to Claim 1, further comprising:
 - a logic section, which is arranged above the internal region,
 - wherein the logic section beingis electrically connected to the power section via bonding connections.

3. (Currently Amended) [[C]]A circuit arrangement according to Claim 2, further comprising[:]

- a third metallic ~~board~~body, ~~which covers~~covering the internal region and ~~is~~ arranged above the component producing less heat,
- ~~wherein the board~~said third metallic body having at least one opening above the internal region and the component producing less heat being electrically connected to the ~~board~~third metallic body via a first wired bond, which is led through the opening, and
- a carrier, ~~which is~~ arranged in an electrically insulating manner above the internal region and above the ~~board~~third metallic body,
- ~~wherein~~ the surface of the carrier facing the ~~board~~third metallic body having an indentation in the region of the first wired bond, to accommodate the first wired bond,
- ~~wherein~~ the surface of the carrier facing away from the ~~board~~third metallic body being essentially flat, and
- ~~wherein~~ the logic section ~~being~~ arranged in an electrically insulating manner on the surface of the carrier facing away from the ~~board~~third metallic body.

4. (Currently Amended) [[C]]A circuit arrangement according to Claim 3,
- wherein the carrier ~~being~~comprises essentially ~~made of~~ aluminum.

5. (Currently Amended) [[C]]A circuit arrangement according to Claim 1, further comprising:

- a third metallic ~~board~~body ~~which covers~~body covering the internal region ~~and is~~ arranged above the component producing less heat,
wherein
 - the ~~board comprising~~third metallic body comprises at least one opening above the internal region,
 - the component producing less heat being embodied as a capacitor and being electrically connected to the ~~board~~third metallic body via a first wired bond, which is led through the opening,

- the heat-generating components being embodied as bare first chips and second chips, each containing a transistor, ~~with the first chips being mounted on at least one first metallic body and the second chips being mounted on a second metallic body,~~
 - ~~the first body being embodied as a bar, which runs along the outer edge of the heat sink,~~
 - ~~the second body being embodied as a board, which covers the internal region and inner edge of the heat sink,~~
 - ~~the board being arranged in an electrically insulating manner on the second body,~~
 - ~~the second body having a first opening above the internal region, which is arranged under the opening of the board and through which the first wired bond is led,~~
 - ~~the second body having at least one second opening above the internal region,~~
 - ~~the component producing less heat being electrically connected to the second body via a second wired bond, which is led through the second opening,~~
- the first chips being electrically connected to the ~~board~~first metallic body via bonding connections, and
- the second chips being electrically connected to the ~~first body~~second metallic body via bonding connections.

6. (Cancelled)

7. (Cancelled)

8. (Cancelled)

9. (Currently Amended) [[C]]A circuit arrangement according to Claim [[5]]1,
- wherein the first metallic body, the second metallic body and the third metallic bodyboard ~~being are comprised of~~ essentially ~~made of~~ copper.

10. (New) A circuit arrangement comprising:
 - a set of first chips,
 - a set of second chips
 - a heat sink having an inner top surface region and an outer top surface region of lesser area,
 - a first metallic body arranged on top of the heat sink and substantially covering the inner top surface region of the heat sink, and
 - a set of metallic bodies arranged on top of the heat sink running along the outer top surface region of the heat sink and surrounding the first metallic body, wherein the first chips are mounted on the first metallic body and the second chips are mounted on the set of metallic bodies.
11. (New) The arrangement of claim 10, wherein the first metallic body and the set of metallic bodies comprise copper.
12. (New) The arrangement of claim 10, wherein the chips are electrically connected to the metallic body and bodies via bonding connections.
13. (New) The arrangement of claim 10, wherein the first metallic body and the set of metallic bodies comprise aluminum.
14. (New) The arrangement of claim 10, wherein the first chips have no packaging.
15. (New) The arrangement of claim 10, wherein the second chips have no packaging.
16. (New) The arrangement of claim 10, wherein the chips have no packaging.
17. (New) The arrangement of claim 10, wherein the first chips comprise a transistor.

18. (New) The arrangement of claim 10, wherein the second chips comprise a transistor.

19. (Allowable) A circuit arrangement comprising:

- a power section, which comprises heat-generating components and at least one component producing less heat,
- the component producing less heat being arranged in an internal region of the circuit arrangement, and
- the heat-generating components being arranged around the internal region and being mounted on first and second metallic bodies acting as electrical conductors, said bodies being electrically connected to the heat-generating components,
- the bodies are arranged in an electrically insulating manner in the region of the heat-generating components on a heat sink, in order to cool the heat-generating components,
- the heat sink running underneath the internal region of the circuit arrangement with the components producing less heat,
- a third metallic body comprising a board covering the internal region and arranged above the component producing less heat,
- the board comprising at least one opening above the internal region,
- the component producing less heat being embodied as a capacitor and being electrically connected to the third metallic board via a first wired bond, which is led through the opening,
- the heat-generating components being embodied as bare first and second chips, each containing a transistor and being mounted on the two metallic bodies, the first chips mounted on the first metallic body comprising a board, the second chips mounted on the second metallic body comprising a bar,
- the first metallic body running along the outer edge of the heat sink,
- the second metallic body covering the internal region and inner edge of the heat sink,
- the first chips electrically connected to the first metallic body via bonding connections, and

- the second chips electrically connected to the second metallic body via bonding connections.

20. (Allowable) A circuit arrangement comprising:

- a power section, which comprises heat-generating components and at least one component producing less heat,
- the component producing less heat being arranged in an internal region of the circuit arrangement, and
- the heat-generating components being arranged around the internal region and being mounted on at least one metallic body acting as an electrical conductor, said body being electrically connected to the heat-generating components, wherein
 - the body is arranged in an electrically insulating manner in the region of the heat-generating components on a heat sink, in order to cool the heat-generating components,
 - the heat sink running underneath the internal region of the circuit arrangement with the components producing less heat,
 - a logic section, arranged above the internal region,
 - said logic section electrically connected to the power section via bonding connections.